



**European Committee
of the Regions**

ECON-VIII/019

**BRIEFING DOCUMENT
and Rapporteur's Questionnaire**

Commission for Economic Policy

EU Chips Act 2.0

Rapporteur: **Thomas Gottfried Schmidt** (DE/EPP)
Member of Saxon State Parliament

Deadline for submitting contributions to this briefing document:
The rapporteur requests that submissions to the questionnaire
be sent **no later than September 7, 2026**
to the ECON Secretariat at econ@cor.europa.eu, Audrey.Parizel@cor.europa and to
adr@smr.sachsen.de
(preferably in English or German)

Reference documents:

Proposal for a Regulation of the European Parliament and of the Council on a framework for measures to strengthen the Union's semiconductor ecosystem and repealing Regulation (EU) 2023/1781 (Chip Regulation 2.0), COM(2026)504 final, dated June 3, 2026

Annexes to the Proposal for a Regulation of the European Parliament and of the Council on a framework for measures to strengthen the Union's semiconductor ecosystem and repealing Regulation (EU) 2023/1781 (Chip Regulation 2.0), COM(2026)504 final of June 3, 2026, Annexes 1 through 7,

[EUR-Lex - 52026PC0504 - EN - EUR-Lex](#)

Briefing Document and Rapporteur's Questionnaire
Commission for Economic Policy (ECON)
Chips Act 2.0

I. Introduction

As the global semiconductor market is expected to reach a volume of EUR 1.37 trillion by 2030, with AI-related components accounting for around 70% of this growth, the EU is now raising its ambitions and seeking to capture a larger share of this growth while at the same time reducing the vulnerabilities associated with external dependencies. This is addressed through the following four initiatives: European Chips Act 2.0, Cloud & AI Development Act, Open-Source Strategy and Strategic Roadmap for Digitalisation and AI in the Energy Sector.

On 3 June 2026, the European Commission published its proposal for an “EU Chips Act 2.0”. In essence, the EU Chips Regulation 2.0 shifts the EU’s semiconductor strategy away from building basic capacities and establishing governance structures under the first Chips Act towards a more operationally oriented industrial-policy framework aimed at translating research results into large-scale production. The main new elements include a more demand-driven approach, broader coverage of the value chain, clearer rules for first-of-a-kind and strategic projects, faster permitting procedures, the “Semiconductor Regions of Excellence” label and network, a business-to-business supply-chain platform, and further-developed crisis-preparedness instruments.

II. Short Summary of the European Commission's proposal

The “Chips Act 2.0” pursues two overarching objectives:

1. Increasing the competitiveness of the European semiconductor value chain;
2. Improving crisis preparedness to ensure the EU’s security of supply.

Chapter 1 – General Provisions describes the subject matter and sets out the key definitions. The updated definition of a “First-of-a-Kind” initiative and the 5 pilot lines are particularly important, as they are defined much more broadly than under the “Chips Act 1.0”. ECA 2.0 covers facilities or processes related to equipment, key components, semiconductor intermediate products, electronics manufacturing, as well as chip-design activities focused on integration and manufacturing, thereby facilitating access to state aid.

Chapter 2 confirms the continuation and further development of the “Chips for Europe” Initiative as “**Chips for Europe Initiative 2.0**” with a stronger focus on industrialisation, particularly in leading-edge technologies and next-generation semiconductor technologies, on demand orientation, and on translating cutting-edge research into market deployment.

The Initiative comprises six components:

1. development capacities for integrated semiconductor technologies, including the expansion of the virtual design platform and support for ambitious strategic development projects of high relevance to the EU;
2. **pilot lines** for innovative production, testing and experimentation;
3. advanced technology and **engineering capacities for quantum chips**;

4. **a network of competence centres** and skills-development measures;
5. **measures under the “Chips Fund” to improve access to capital** for start-ups, scale-ups and SMEs;
6. as well as a new component addressing advanced design, prototyping and industrial deployment capacities for **photonic** integrated circuit technologies.

Chapter 2 also introduces demand-side instruments such as **“Grand Challenges”, the “Demand Forum” and “Demand Accelerators”**. These are intended to link semiconductor developers more closely with user industries, support co-design, accelerate market deployment and stimulate early demand for European technologies. The Initiative would continue to be supported by “Horizon Europe” and the “Digital Europe” Programme under the current MFF and possibly under the next MFF.

Chapter 3 on security of supply and demand sets out the framework for **European initiatives and strategic projects in the field of semiconductor technology**. These should meet criteria relating to EU added value, cross-border relevance, resilience, prosperity, technological sovereignty and technological leadership.

A key element of this chapter is the clarification of **“First-of-a-Kind”** initiatives and the possibility of **recognising European initiatives in the field of semiconductor technology across the entire semiconductor value chain** (the “whole-chain ecosystem” approach).

Chapter 3 also introduces **an accelerated permitting procedure** for European semiconductor-technology initiatives and strategic projects. Member States would have to organise the granting of permits through a single procedure and via **a one-stop shop**, with a **maximum duration of 12 months**. Finally, Chapter 3 contains measures to **strengthen supply-chain** resilience, particularly **in public procurement** and in risk-exposed sectors.

Chapter 4 on monitoring and crisis response provides for a **strategic mapping system** covering dependencies, vulnerabilities, key customer industries, critical infrastructure, supply-chain segments, skills bottlenecks and future needs. The Commission would use this mapping for regular monitoring of the value chain.

An important new instrument is the **“Business-to-Business Semiconductor Supply Chain Platform”**. The proposal describes it as a digital twin of the semiconductor supply chain designed to improve transparency and help companies identify risks and strengthen their resilience. Chapter 4 **also further specifies the crisis mechanism**.

Chapter 5 on governance provides for the continuation of the **European Semiconductor Board**, which is composed of representatives of the Member States and chaired by the Commission. The Board advises the Commission with regard to the “Chips for Europe 2.0” Initiative, the assessment of European semiconductor-technology initiatives and strategic projects. **Where appropriate, the Chair may involve stakeholder organisations, including the network of European Semiconductor Regions of Excellence**. Furthermore, the Chair may establish subgroups and appoint observers.

The proposal also provides for the establishment of an **Industrial Alliance for Semiconductors**. The Commission is to chair the Alliance, which is intended to demonstrate strong industry involvement in EU governance.

III. Rapporteur's Questionnaire

- **How do you assess ECA 1.0 for your region?** Who participated in the evaluation of the European Commission? What positive aspects resulted from ECA 1.0? What was missing?
- **State aid for investment projects** based on the "first-of-a-kind" criterion is expected to remain available. How should support under the ECA 2.0 be designed? How can State aid procedures be simplified and accelerated? How should the ECA 2.0 be financed under the Multiannual Financial Framework (MFF) from 2028 onwards?
- **What specifically do you expect from an ECA 2.0** for the semiconductor clusters located in your region? What specific design of the funding instruments does the research and development landscape, or the manufacturers and suppliers, require? In which industrial sectors or research fields should the approach of “reinforcing current European strengths” be applied in particular?
- **How do you assess the European Commission's proposal for an ECA 2.0?** Does it address the needs of regional semiconductor ecosystems and provide the right instruments for implementation at regional level? Who needs to create which conditions in order to implement the substantial expansion of the objectives under ECA 2.0?
- **With ECA 2.0, the European Commission pursues four objectives:** (1) improving conditions for investment and competitiveness, (2) stimulating demand and industry uptake, (3) strengthening supply-side measures and (4) strengthening resilience and reducing dependencies. In your view, are these the right objectives?
- Compared with the European Chips Act 1.0, the proposal of the European Chips Act 2.0 takes a **significantly broader approach and addresses a substantially larger spectrum of the semiconductor value chain**. In your view, where does this approach go too far? Where are even the wrong priorities being set, and which areas of the European semiconductor industry or value chain are nevertheless insufficiently taken into account or missing entirely?
- Which **additional priorities or fundamental prerequisites**, such as skilled labour, infrastructure, energy supply and grid capacity, should be taken into account in order to ensure successful implementation?
- The European Commission wants to create better **framework conditions for semiconductor investment at regional level**. What framework conditions are needed, and where, so that regions can successfully attract semiconductor investment? How should these framework conditions be designed?
- How can ECA 2.0 better link semiconductor technologies **with industrial AI applications, advanced manufacturing and energy-efficient digitalisation** along European value chains?
- How and which **advanced and innovative chip technologies**, such as photonics for energy-saving chips or smaller semiconductor nodes, should be supported? How do you intend to benefit from the focus on latest-generation chips such as AI chips, quantum chips and photonic chips?

- Which requirements should form part of the “**grand challenges**” **criterion**? What impacts should these have?
- How do you assess the planned “**European Semiconductor Region of Excellence**” **label**, and what (new) opportunities do you see it creating for your company/institution? How do you assess the planned **network** of the “European Semiconductor Region of Excellence”?
- The European Commission wants to strengthen **research, innovation and skills development** across the entire semiconductor ecosystem.
 - How should the research infrastructures that have been established (especially the Pilot Lines) be taken forward?
 - How can advanced and innovative chip technologies such as photonics for energy-saving chips or semiconductor process nodes below 10 nanometres be supported in a more targeted way?
 - Expanded testing and verification capacities can make the EU’s entire semiconductor ecosystem more resilient. What is needed to expand these capacities?
 - How can advanced and innovative chip technologies such as photonics for energy-saving chips or semiconductor process nodes below 10 nanometres be supported in a more targeted way?
 - How can Europe better address the shortage of skilled workers in the semiconductor sector and provide more targeted support for talent?
 - How can EU-wide access to strategic semiconductor infrastructures, such as pilot lines, testing facilities and design platforms, be improved?
- From your perspective, can increased **back-end production** in Europe enhance supply-chain resilience and help ensure security of supply in the event of disruptions? If yes: In which areas and why should we build up back-end production in Europe? What promotes the development of a backend ecosystem? If no: why not?